Material Declaration Datasheet

Restriction on Hazardous Substances (RoHS) Compliance

Manufacturer:	Intel Corporation	Date:	27 June 2005
Equipment type:	desktop motherboard (cpu board)	Lead-free product:	Yes, containing (2) SLI chipsets
Model designation:	D955XCS	Product weight:	635.2 grams

RoHS Definitions

* Quantity limit of 0.1% by mass (1000 PPM) for; Lead (Pb); Mercury; Hexavalent Chromium; Polybrominated Biphenyls (PBB); Polybrominated Diphenyl Ethers (PBDE).
* Quantity limit of 0.01% by mass (100 PPM) for Cadmium.

Intel understands RoHS requires Lead and other materials banned in RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU, or (2) an approved/pending exemption applies. Note, RoHS implementation details are subject to change.

RoHS Declaration

☐ This product does not contain RoHS restricted substances per the RoHS definitions above. This product is RoHS directive compliant.

☑ This product does contain RoHS restricted substance(s) per the definitions above, but has exemption status. This product is RoHS directive compliant by the following exemption: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

☐ This product does contain RoHS restricted substance(s) above the threshold level. RoHS exemptions are not applicable. This product is not RoHS directive compliant.

Where the product is declared compliant with RoHS directive requirements, the product has been verified to be in conformance with EU directive 2002/95/EC as currently understood. To the best of our knowledge, the information contained in this declaration is true and correct.

LEVEL A MATERIALS AND SUBSTANCES

Materials from Annex A of the EIA/EICTA/JGPSSI Material Composition Declaration Guide and listed in the table below are not contained in this product in quantities above the threshold level for these materials as stated in the EIA/EICTA/JGPSSI Material Composition Declaration Guide, nor intentionally added to this product.

Asbestos	Mercury/Mercury Compounds	Polychlorinated Naphthalenes
Azo colorants	Ozone Depleting Substances	Radioactive Substances
Cadmium /Cadmium Compounds	Polybrominated Biphenyls (PBBs)	Shortchain Chlorinated Paraffins
Hexavalent Chromium	Polybrominated Diphenylethers (PBDEs)	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Hexavalent Chromium Compounds	Polychlorinated Biphenyls (PCBs)	Tributyl Tin Oxide (TBTO)

This product contains lead or lead compounds above the threshold limit of 1000ppm - No

Material / Substance	Description of Use	Location in Product	Material Concentration
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LEVEL B MATERIALS AND SUBSTANCES

Antimony/Antimony Compounds	Beryllium/Beryllium Compounds	Brominated Flame Retardants
Arsenic/Arsenic Compounds	Bismuth/Bismuth Compounds	Nickel/Nickel Compounds

If this product contains materials listed in Annex B of the EIA/EICTA/JGPSSI Material Composition Declaration Guide above the threshold level of 1000 ppm, those materials/substances are listed below.

Material / Substance	Description of Use	Location in Product	Material Concentration
antimony	flame retardant	board	5,430 ppm
nickel	plating	component plating	3,070 ppm
brominated flame retardant (TBBPA)	flame retardant	board	46,100 ppm

COMMENTS

1. The data reported for Level A and B materials and/or substances are determined through analytical testing of a representative sample of the product.
2. Individual test results may vary due to differences in production and /or sensitivities of analytical testing methods. Data shown reflect analytical testing intended to validate Intel's RoHS compliance systems. Additionally, RoHS compliance at the homogenous material level is based on Supplier's Declarations of Conformance.
3. This material declaration datasheet is product specific. Like product variants or alternate skus are assumed to be same or similar.
4. Material mass can be estimated by multiplying concentration (in ppm) by product weight.
5. The remainder of this product consists of non-reportable metals (e.g., copper, tin), epoxy resin and other non-metal materials.